19-4215; Rev 2; 4/11

EVALUATION KIT AVAILABLE

Programmable, High-Speed, Multiple Input/Output LVDS Crossbar Switches

General Description

The MAX9132/MAX9134/MAX9135 high-speed, multiple-port, low-voltage differential signaling (LVDS) crossbar switches are specially designed for digital video and camera signal transmission. These switches have a wide bandwidth, supporting data rates up to 840Mbps. The MAX9132 has three input ports and two output ports, the MAX9134 has three input ports and four output ports, and the MAX9135 has four input ports and three output ports. The digital video or camera signal can go through the switches from an input port to one or multiple output ports.

The MAX9132/MAX9134/MAX9135 switch routing is programmable through either an I²C interface or a Local Interconnect Network (LIN) serial interface. In addition, the MAX9134/MAX9135 provide pins to set switch routing. These pins also set the initial conditions for the I²C mode. To generate more input or output ports, these switches can be connected in parallel or in cascade.

The MAX9132/MAX9134/MAX9135 operate from a +3.3V supply and are specified over the -40° C to $+105^{\circ}$ C temperature range. The MAX9134/MAX9135 are available in a 32-pin (5mm x 5mm) TQFP package, while the MAX9132 is available in a 20-pin (6.5mm x 4.4mm) TSSOP package. The input/output port pins are rated up to ± 25 kV ESD for the ISO Air-Gap Discharge Model, ± 15 kV ESD for the IEC Air-Gap Discharge Model, and ± 10 kV for the ESD Contact Discharge Model. All other pins support up to ± 3 kV ESD for the Human Body Model.

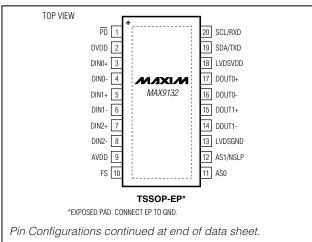
Applications

Digital Video in Automotive Video/Audio Distribution Systems Camera Surveillance Systems High-Speed Digital Media Routing Navigation System Displays

Features

Supports Up to 840Mbps Data Rate at Each Port

- Nonactivated Ports are in High-Impedance State for Easy Port Expansion
- Programmable Preemphasis on LVDS Outputs
- Self Common-Mode Biasing on LVDS Inputs
- Three Selectable Approaches for Switch Routing: I²C Interface LIN Interface Programmable Pins (MAX9134/MAX9135)
- ♦ ±25kV ESD Protection
- +3.3V Supply Voltage
- ♦ -40°C to +105°C Operating Temperature Range



Pin Configurations

Ordering Information

				•
PART	PIN-PACKAGE	INPUTS	OUTPUTS	ROUTE CONTROL
MAX9132GUP+	20 TSSOP-EP*	3	2	I ² C, LIN
MAX9132GUP/V+	20 TSSOP-EP*	3	2	I ² C, LIN
MAX9134GHJ+	32 TQFP-EP*	3	4	I ² C, LIN, Pins
MAX9135GHJ+	32 TQFP-EP*	4	3	I ² C, LIN, Pins

Note: Devices are specified over the -40°C to +105°C temperature range.

+Denotes a lead(Pb)-free/RoHS-compliant package.

*EP = Exposed pad.

/V denotes an automotive qualified part.

_ Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

V _{DD} to GND0.3V to +4.0V All Pins to GND0.3V	IEC 61000-4-2 (RD = 330Ω , CS = 150pF) Contact Discharge
Short-Circuit Duration (all outputs)Continuous	(DIN_, DOUT_) to GND±10kV
Continuous Power Dissipation ($T_A = +70^{\circ}C$)	Air-Gap Discharge
32-Pin TQFP (derate 27.8mW/°C above +70°C)2222mW	(DIN_, DOUT_) to GND±15kV
20-Pin TSSOP (derate 26.5mW/°C above +70°C)2122mW	ISO 10605 (R _D = 2kΩ, CS = 330pF)
Operating Temperature Range40°C to +105°C	Contact Discharge
Junction Temperature+150°C	(DIN_, DOUT_) to GND±10kV
Storage Temperature Range65°C to +150°C	Air-Gap Discharge
ESD Protection	(DIN_, DOUT_) to GND±25kV
Human Body Model (RD = $1.5k\Omega$, CS = $100pF$)	Lead Temperature (soldering, 10s)+300°C
All Other Pins Including SCL, SDA to GND±2kV	Soldering Temperature (reflow)+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

PACKAGE THERMAL CHARACTERISTICS (Note 1)

20 TSSOP-EP	
Junction-to-Ambient Thermal Resistance (0JA)37.7°C/W	
Junction-to-Case Thermal Resistance (0JC)2°C/W	

32 TOFP-EP Junction-to-Case Thermal Resistance (0JC)......4°C/W

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a fourlayer board. For detailed information on package thermal considerations, refer to www.maxim-ic.com/thermal-tutorial.

DC ELECTRICAL CHARACTERISTICS

(VAVDD = VDVDD = VLVDSVDD = +3.0V to +3.6V, TA = -40°C to +105°C, unless otherwise noted. Typical values are at VAVDD = VDVDD = V_{LVDSVDD} = +3.3V, T_A = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	ТҮР	МАХ	UNITS
Supply Voltage	V _{DD}			3.0		3.6	V
Supply Current	IAVDD,	Outputs switching at	MAX9132		60	80	mA
Supply Current	IDVDD, ILVDSVDD	20MHz	MAX9134/MAX9135		86	100	ШA
SINGLE-ENDED CMOS INPUTS	PD, FS, RXD)					
Input High Level	VIH1			2.0			V
Input Low Level	VIL1					0.8	V
Input High Current	I _{IN1}	$V_{IN} = 0$ to V_{DD}		-20		+20	μA
SINGLE-ENDED OUTPUTS (TXD,	AS1/NSLP)						
Output High Level	V _{OH}			V _{DD} - 0.4			V
Output Low Level	V _{OL}	$I_{OL} = 4mA$				0.4	V
3-LEVEL INPUTS (S5–S0, AS0, A	S1)						
Input High Level	V _{IH3}			2.5			V
Input Low Level	V _{IL3}					0.8	V
Input Open Level	V _{IO3}	Measured at the input	1.2	1.45	1.9	V	
Input Current	I _{L3} , I _{H3}	$V_{IL3} = 0V \text{ or } V_{IH3} = V_{I}$	-20		+20	μA	

DC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{AVDD} = V_{DVDD} = V_{LVDSVDD} = +3.0V$ to +3.6V, $T_A = -40^{\circ}C$ to +105°C unless otherwise noted. Typical values are at $V_{AVDD} = V_{DVDD} = V_{LVDSVDD} = +3.3V$, $T_A = +25^{\circ}C$.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
DIFFERENTIAL INPUTS (DIN_)		•				
Differential Input High Threshold	VIDH	$V_{ID} = V_{IN+} - V_{IN-}$			100	mV
Differential Input Low Threshold	VIDL	$V_{ID} = V_{IN+} - V_{IN-}$	-100			mV
Common Input Voltage	VCOM	$V_{COM} = (V_{IN+} - V_{IN-})/2$	1.00	1.29	1.60	V
Input Current	I _{IN+} , I _{IN-}		-50		+50	μA
DIFFERENTIAL OUTPUTS (DOUT	_)					
Differential Output Voltage	Vod	50 Ω load, no preemphasis	250	3.65	450	mV
Change in V _{OD} Between Complementary Output States	Iav _{od} i		0	1	35	mV
Output Common-Mode Voltage	VCOM		1.125	1.29	1.475	V
Change in V _{COM} Between Complementary Output States	IAV _{COM} I ⁴		0	1	35	mV
Output Short-Circuit Current	I _{OS}	Two output pins connected to GND	-15	-7		mA
SERIAL-INTERFACE INPUT, OUT	PUT (SCL, S	SDA)				
Input High Level	VIH		0.7 x V _{DD}			V
Input Low Level	VIL				0.3 x V _{DD}	V
High-Level Output Leakage Current	ILEAKH	Open drain with $1k\Omega$ pullup to V _{DD}			1	μA
Low-Level Output	V _{OL}	I _{OL} = 3mA			0.4	V
Input Capacitance	CI			10		рF

AC ELECTRICAL CHARACTERISTICS

 $(V_{AVDD} = V_{DVDD} = V_{LVDSVDD} = +3.0V \text{ to } +3.6V, \text{ T}_{A} = -40^{\circ}\text{C} \text{ to } +105^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at V_{AVDD} = V_{DVDD} = V_{LVDSVDD} = +3.3V, \text{ T}_{A} = +25^{\circ}\text{C}.) \text{ (Notes 3, 4)}$

PARAMETER	SYMBOL	CONDITIONS		ТҮР	MAX	UNITS		
DIFFERENTIAL SIGNALS (DOUT_)								
Output-to-Output Skew	tsĸ	$R_L = 100\Omega$ differential		50	250	ps		
Rise Time	tR	20% to 80% of the signal swing; $R_L = 50\Omega$ differential ($R_L = 100\Omega$ double termination), $C_L = 5pF$		0.3	0.4	ns		
Fall Time	tF	20% to 80% of the signal swing; $R_L = 50\Omega$ differential ($R_L = 100\Omega$ double termination), $C_L = 5pF$		0.3	0.4	ns		
Duty Cycle	D	Input duty cycle 50%; 840Mbps clock pattern	45		55	%		

AC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{AVDD} = V_{DVDD} = V_{LVDSVDD} = +3.0V \text{ to } +3.6V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C, \text{ unless otherwise noted. Typical values are at V_{AVDD} = V_{DVDD} = V_{LVDSVDD} = +3.3V, T_A = +25^{\circ}C.) (Notes 3, 4)$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Peak-to-Peak Jitter	÷.	V_{ID} = 200mV, V_{COM} = 1.2V, 840Mbps clock pattern; input transition time (20% to 80%) = 200ps		10	30	ps
(Preemphasis On)	tj	V_{ID} = 200mV, V_{COM} = 1.2V, 840Mbps 2 ²³ - 1 PRBS pattern; input transition time (20% to 80%) = 200ps		85	180	ps
Propagation Delay	t _D			2		ns
LVDS Switchover Time	t LON	Switchover time from one channel to another			100	ns
LVDS with Preemphasis Amplitude	IV _{ODPE} I	50Ω differential (100Ω double termination) load, 840Mbps	335	530	680	mV
I ² C TIMING	•	·				•
CLK Frequency	fSCL				400	kHz
Start Condition Hold Time	thd:sta	(Figure 1)	0.6			μs
Low Period of SCL Clock	tlow	(Figure 1)	1.3			μs
High Period of SCL Clock	thigh	(Figure 1)	0.6			μs
Repeated START Condition Setup Time	tsu:sta	(Figure 1)	0.6			μs
Data Hold Time	thd:dat	(Figure 1)	0		0.9	μs
Data Setup Time	tsu:sta	(Figure 1)	100			ns
Setup Time for STOP Condition	tsu:sto	(Figure 1)	0.6			μs
Bus Free Time	tBUF	(Figure 1)	1.3			μs

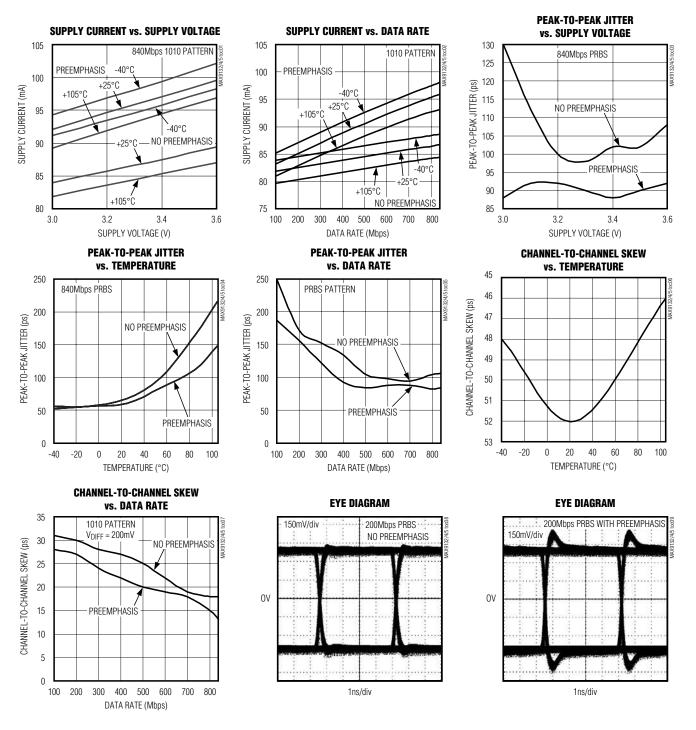
Note 2: Parameters are 100% production tested at $T_A = +25^{\circ}C$, unless otherwise noted.

Note 3: I^2C timing parameters are specified for fast-mode I^2C . Maximum data rate = 400kbps.

Note 4: Parameters are guaranteed by design.

Typical Operating Characteristics

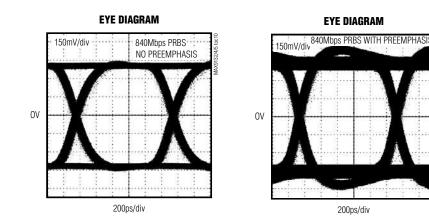
 $(V_{AVDD} = V_{DVDD} = V_{LVDSVDD} = +3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$



M/IXI/M

Typical Operating Characteristics (continued)

 $(V_{AVDD} = V_{DVDD} = V_{LVDSVDD} = +3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$



Pin Description

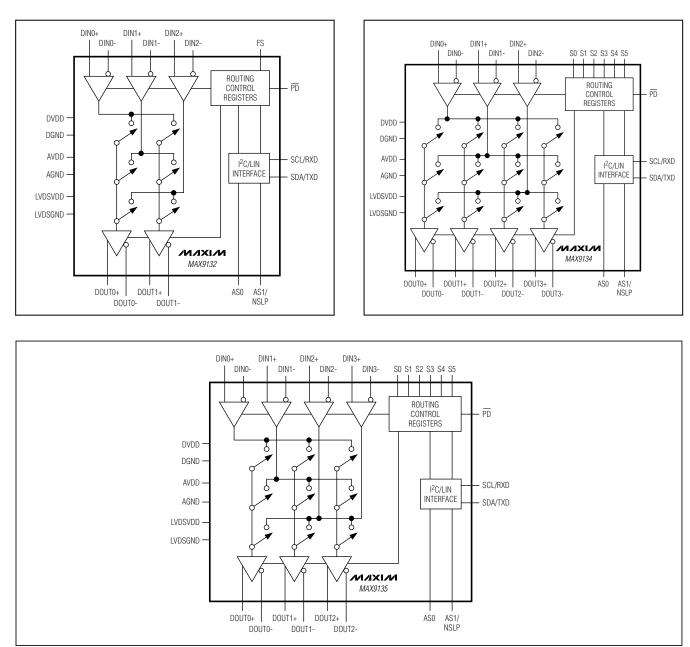
MIXIM

PIN				
MAX9132 TSSOP	MAX9134 TQFP	MAX9135 TQFP	NAME	FUNCTION
1	31	30	PD	Power-Down Input. \overline{PD} = low for power-down. \overline{PD} = high for power-up without preemphasis. Leave \overline{PD} open for power-up with preemphasis on all outputs.
2	32	31	DVDD	Digital Power Supply. Bypass DVDD to DGND with 0.1μ F and 0.01μ F capacitors as close as possible to the device.
3	1	1	DIN0+	Port 0 Positive Input
4	2	2	DIN0-	Port 0 Negative Input
5	3	3	DIN1+	Port 1 Positive Input
6	4	4	DIN1-	Port 1 Negative Input
_	5	_	AGND	Analog Ground
7	6	5	DIN2+	Port 2 Positive Input
8	7	6	DIN2-	Port 2 Negative Input
_	—	7	DIN3+	Port 3 Positive Input
_	_	8	DIN3-	Port 3 Negative Input
9	8	9	AVDD	Analog Power Supply. Bypass AVDD to AGND with 0.1 μ F and 0.01 μ F capacitors as close as possible to the device.
10	_	_	FS	$I^{2}C$ and LIN Interface Selection Input. FS = low for LIN, FS = high for $I^{2}C$.
_	9	10	S0	Routing Selection 0 Input. See Tables 6a and 6b.
_	10	11	S1	Routing Selection 1 Input. See Tables 6a and 6b.
_	11	12	S2	Routing Selection 2 Input. See Tables 6a and 6b.
_	12	13	S3	Routing Selection 3 Input. See Tables 6a and 6b.
11	13	14	AS0	3-Level I ² C Address Selection 0 Input (Table 3) or LIN Identifier Selection 0 Input (Table 4)

Pin Description (continued)

PIN				
MAX9132 TSSOP	MAX9134 TQFP	MAX9135 TQFP	NAME	FUNCTION
12	14	15	AS1/NSLP	3-Level I ² C Address Selection 1 Input (in I ² C Mode, Table 3). In LIN bus mode, it becomes an NSLP output, the sleep mode activation pin (active low) to the LIN bus driver.
13	16, 25	19, 24	LVDSGND	LVDS Ground
_	17	—	DOUT3-	Port 3 Negative Output
_	18	_	DOUT3+	Port 3 Positive Output
_	19	17	DOUT2-	Port 2 Negative Output
_	20	18	DOUT2+	Port 2 Positive Output
14	21	20	DOUT1-	Port 1 Negative Output
15	22	21	DOUT1+	Port 1 Positive Output
16	23	22	DOUT0-	Port 0 Negative Output
17	24	23	DOUT0+	Port 0 Positive Output
18	15, 26	16, 25	LVDSVDD	LVDS Supply Input. Bypass LVDSVDD to LVDSGND with 0.1 μ F and 0.01 μ F capacitors as close as possible to the device.
19	27	26	SDA/TXD	I ² C Data Link Input/LIN Tx Output. SDA/TXD becomes SDA when in I ² C mode and TXD when in LIN mode.
20	28	27	SCL/RXD	I ² C Clock/LIN Rx Input. SCL/RXD becomes SCL when in I ² C mode and RXD when in LIN mode.
_	29	28	S5	Routing Selection 5 Input. See Tables 6a and 6b.
_	30	29	S4	Routing Selection 4 Input. See Tables 6a and 6b.
_	_	32	DGND	Digital Ground
_	_		EP	Exposed Pad. Internally connected to GND. Connect to a large ground plane to maximize thermal performance.





REGISTER ADDRESS (HEX)	READ/ WRITE	LIN INTERFACE DESCRIPTION	I ² C DESCRIPTION
0x00	R	LIN Status Register	Reserved
0x01	R/W	Switch Control Register 1	Switch Control Register 1
0x02	R/W	Switch Control Register 2 (MAX9134/MAX9135 only)	Switch Control Register 2 (MAX9134/MAX9135 only)
0xFF	W	Reserved	Route Activation Register

Table 1. Register Address Map

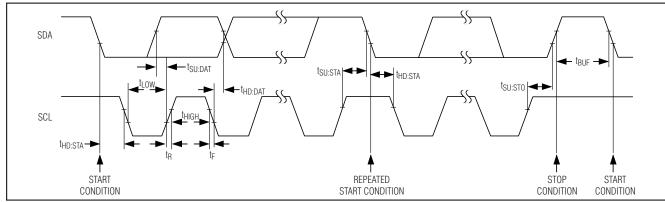


Figure 1. I²C Serial-Interface Timing Details

Detailed Description

The MAX9132/MAX9134/MAX9135 high-speed, multiple-port, low-voltage differential signaling (LVDS) crossbar switches are specially designed for digital video and camera signal transmission. These switches have a wide bandwidth, supporting data rates up to 840Mbps. This allows the use of MAX9132/MAX9134/ MAX9135 with LVDS serializers/deserializers (SerDes) to create a complete video or camera network. The MAX9132 has three input ports and two output ports, the MAX9134 has three input ports and four output ports, and the MAX9135 has four input ports and three output ports. The video or camera signal can go through the switch from an input port to one or multiple output ports.

The MAX9132/MAX9134/MAX9135 switch routing is programmable through either an I²C interface or a Local Interconnect Network (LIN) serial interface. AS0 and AS1 set the slave addresses for either of these modes, allowing several devices on a bus simultaneously. In addition, the MAX9134/MAX9135 provide 3-level pins S[5:0] to set switch routing and the initial conditions for I²C mode. To improve the signal integrity, all the LVDS outputs feature selectable preemphasis.

Initial Power-Up

On power-up, all control registers have a value of 0x00. For the MAX9134/MAX9135, leaving S[5:0] unconnected, allows control through the LIN interface with all outputs deactivated. Otherwise, the switch runs in pin-control mode with S[5:0] controlling the switch routing. The I²C is also active while the device is in pincontrol mode. Successful routing through I²C overrides the pin settings. For more details, see the I²C Interface section. For the MAX9132, the FS input determines which interface is active.

Register Description

There are four 1-byte control registers in the MAX9132/MAX9134/MAX9135. These registers control the routing of the switch. Table 1 describes the register map for both I²C and LIN. When the MAX9132/MAX9134/MAX9135 operate in LIN mode, register 0x00 acts as an error flag register. Its function is described in detail in Table 5. In either I²C or LIN mode, the control registers (0x01, 0x02) program the MAX9132/MAX9134/MAX9135 switch routing control. In addition, these registers can individually activate and deactivate preemphasis for each output port. Table 2a describes the routing for the MAX9132/MAX9134 and Table 2b for the MAX9135. For I²C programming, register 0xFF controls the activation of routing.



Table 2a. I²C/LIN Switch Routing Control Registers for the MAX9132/MAX9134

REGISTER ADDRESS	REGISTER BIT(S)	DESCRIPTION	VALUE	FUNCTION
	D7	DOUT1 Proomphasia	0	DOUT1 preemphasis off
	DT	DOUT1 Preemphasis	1	DOUT1 preemphasis on
			000	DOUT1 in high impedance
		DOUT1 Routing	001	DOUT1 connected to DIN1
	D[6:4]	Connection	010	DOUT1 connected to DIN0
0x01			011	DOUT1 connected to DIN2
0.001	D3	DOUT0 Preemphasis	0	DOUT0 preemphasis off
	03	DOUTO Preemphasis	1	DOUT0 preemphasis on
	D[2:0]		000	DOUT0 in high impedance
		DOUT0 Routing Connection	001	DOUT0 connected to DIN1
			010	DOUT0 connected to DIN0
			011	DOUT0 connected to DIN2
	D7	DOUT3 Preemphasis	0	DOUT3 preemphasis off
			1	DOUT3 preemphasis on
			000	DOUT3 in high impedance
	D[6:4]	DOUT3 Routing	001	DOUT3 connected to DIN1
	D[0.4]	Connection	010	DOUT3 connected to DIN0
0x02			011	DOUT3 connected to DIN2
(MAX9134 only)	D3	DOLIT2 Proomphasia	0	DOUT2 preemphasis off
	Do	DOUT2 Preemphasis	1	DOUT2 preemphasis on
			000	DOUT2 in high impedance
	0.01	DOUT2 Routing	001	DOUT2 connected to DIN1
	D[2:0]	Connection	010	DOUT2 connected to DIN0
			011	DOUT2 connected to DIN2

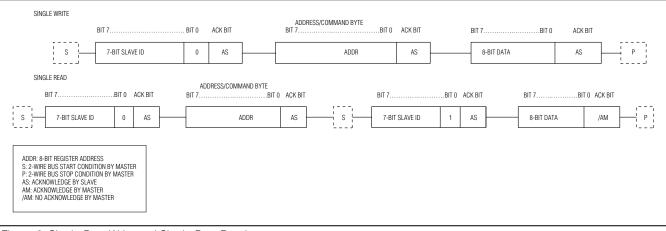


Figure 2. Single-Byte Write and Single-Byte Read

REGISTER ADDRESS	REGISTER BIT(S)	DESCRIPTION	VALUE	FUNCTION
	07		0	DOUT1 preemphasis off
	D7	DOUT1 Preemphasis	1	DOUT1 preemphasis on
			000	DOUT1 not connected
			001	DOUT1 connected to DIN1
	D[6:4]	DOUT1 Routing Connection	010	DOUT1 connected to DIN0
		Connection	011	DOUT1 connected to DIN2
001			100	DOUT1 connected to DIN3
0x01			0	DOUT0 preemphasis off
	D3	DOUT0 Preemphasis	1	DOUT0 preemphasis on
	D[2:0]	DOUT0 Routing	000	DOUT0 not connected
			001	DOUT0 connected to DIN1
			010	DOUT0 connected to DIN0
		Connection	011	DOUT0 connected to DIN2
			100	DOUT0 connected to DIN3
	D[7:4]	Reserved	0000	Set these bits to 0000
	D 0		0	DOUT2 preemphasis off
	D3	DOUT2 Preemphasis	1	DOUT2 preemphasis on
000			000	DOUT2 not connected
0x02			001	DOUT2 connected to DIN1
	D[2:0]	DOUT2 Routing Connection	010	DOUT2 connected to DIN0
		CONNECTION	011	DOUT2 connected to DIN2
			100	DOUT2 connected to DIN3

Table 2b. I²C Switch Routing Control Registers for the MAX9135

I²C Interface

The MAX9132/MAX9134/MAX9135 operate as slaves that send and receive data through I²C (see Figure 1). The interface uses a serial-data line (SDA) and a serialclock line (SCL) to achieve bidirectional communication between master(s) and slave(s). A master (typically a microcontroller) initiates all data transfers to and from the slave and generates the SCL clock that synchronizes the data transfer. The SDA line operates as both an input and an open-drain output. A pullup resistor, typically 4.7kΩ, is required on SDA. The SCL line operates only as an input. A pullup resistor is required on SCL if there are multiple masters on the I²C interface, or if the master in a single-master system has an opendrain SCL output. Each transmission consists of a START condition sent by a master, followed by the 7-bit slave address plus R/W bit, a register address byte, a data byte, and finally a STOP condition. Table 3 shows the slave address selection by the AS0 and AS1 pins.

Data Format for Writing to the Slave

A write to the MAX9132/MAX9134/MAX9135 comprises the transmission of the slave address with the R/W bit set to 0, followed by at least 1 byte of information. The first byte of information is the command byte. The command byte determines which registers of the MAX9132/MAX9134/MAX9135 are to be written by the next byte, if received. If a STOP condition is detected after the command byte is received, the MAX9132/ MAX9134/MAX9135 take no further action beyond storing the command byte. Any bytes that are received after the command byte are data bytes. The first data byte goes into the internal register of the crossbar switch selected by the command byte (Figure 2). If multiple data bytes are transmitted before a STOP condition is detected, these bytes are generally stored in subsequent MAX9132/MAX9134/MAX9135 internal registers because the command byte address generally autoincrements (Table 1).

Table 3. I²C Slave Addresses

PIN			ADDRESS (HEX)						
AS0	AS1	A[7:5]	A4	A3	A2	A1	A0	ADDRESS (HEX)	
Low	Low	101	0	0	0	0	R/W	0xA0	
Low	Open	101	0	0	0	1	R/W	0xA2	
Low	High	101	0	0	1	0	R/W	0xA4	
Open	Low	101	0	0	1	1	R/W	0xA6	
Open	Open	101	0	1	0	0	R/W	0xA8	
Open	High	101	0	1	0	1	R/W	0xAA	
High	Low	101	0	1	1	0	R/W	0XAC	
High	Open	101	0	1	1	1	R/W	0xAE	
High	High	101	1	0	0	0	R/W	0xB0	

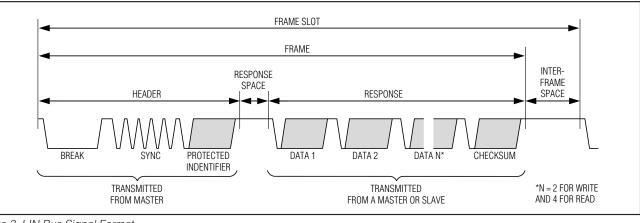


Figure 3. LIN Bus Signal Format



Figure 4. LIN Write and Read Data Frame

Data Format for Reading from the Slave

The MAX9132/MAX9134/MAX9135 are read using the devices' internally stored command bytes as an address pointer, the same way the stored command byte is used as an address pointer for a write. The pointer does not autoincrement after each data byte is read. Initiate a read by writing the command byte to the proper slave address (Figure 2), then send the device's slave address with the R/W bit set to 1. The slave now responds with the contents of the requested register (Figure 2).

LIN Interface

The LIN interface is a low-speed, low-cost interface used in slow control signal traffic in automotive applications. This device is the slave node in the LIN bus cluster and is designed based on the LIN Rev. 1.3 specification. The LIN master sends data to the MAX9132/MAX9134/ MAX9135 LSB first, up to a maximum data rate of 20kbps. The LIN slave node waits for the synchronization pulse, then synchronizes itself to the pulse. The node must then read the identifier and send/receive data bytes to the master, setting the error flag register when necessary. The LIN interface uses the same routing function of the switch control registers (0x01, 0x02) as the I²C inter-



Table 4. LIN Identifiers for Write and Read Operations

AS0	WRI	re id	READ ID		
	ID[5:0]	PID FIELD	ID[5:0]	PID FIELD	
Low	0x08	0x08	0x27	0xE7	
Open	0x0A	0xCA	0x29	0xE9	
High	0x1C	0x9C	0x2B	0x2B	

Table 5. Register 0x00 Error Flag Mapping for LIN

REGISTER BIT(S)	DESCRIPTION	FUNCTION
D[7:5]	Reserved	Reserved
D4	Sync	Sync pulse widths outside the given tolerances detected
D3	Transmit	Value read on RXD different from value transmitted on TXD during a read
D2	Checksum	Checksum sent during a write does not match the expected checksum
D1	Parity	ID parity bit does not match expected parity
D0	Frame	Message frame did not complete within the maximum allowed time

face. The routing action takes place after correct checksum verification. The LIN status register (0x00) holds the error flags for the LIN transceiver. For a write, the master writes 2 bytes of data to the registers (0x01, 0x02). For a read, the slave outputs the contents of registers 0x00, 0x01, and 0x02, along with the stuffing byte at a constant value (0xFF). In either mode, the checksum follows at the end of the data bytes. Figure 3 shows the write and read signal frame format. Figure 4 shows the LIN write and read data frame.

LIN-Protected Identifier

The LIN bus uses the 8-bit protected identifier (PID) to address the slave nodes. Two parity bits (MSBs) along with 6 ID bits (LSBs) make up the PID field. Table 4 defines the sets of the identifiers for the write/read operations of the LIN slave node. AS0 selects the identifiers. AS1/NSLP becomes the NSLP output for activating the LIN driver chip (MAX13020).

LIN Error Handling

Register 0x00 contains the error flags found in the LIN signal by the slave note (Table 5). A successful LIN read resets register 0x00.

Pin Control by S[5:0] (MAX9134/MAX9135)

For the MAX9134/MAX9135, the routing can be controlled by the hardware pins (S[5:0]). If the I²C register 0xFF is not written by 0xFF, then chip routing is determined by S[5:0]. Also, these pins set the initial powerup routing condition of the chip. Table 6a gives the details of the routing control for the MAX9134. Table 6b gives the details of the routing control for the MAX9135. Once the I²C register 0xFF is written by 0xFF, the I²C

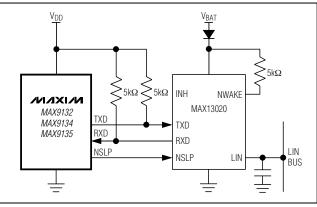


Figure 5. Connecting the MAX9132/MAX9134/MAX9135 to the MAX13020

registers 0x01 and 0x02 take over the routing and the pin (S[5:0]) setting is ignored. After the I²C routing takes place, the pin setting can be changed without affecting the routing. The new pin setting takes effect if the PD pin or the chip supply is toggled. Usually, once I²C controls the routing, there is no value in using the pin routing.

Applications Information

3-Level Inputs

The MAX9132/MAX9134/MAX9135 use several 3-level inputs to control the device. Use three-state logic to realize the 3-level logic using digital control. Alternatively, if a high-impedance output is unavailable, apply a voltage of $V_{DD}/2$ to realize the midlevel high-impedance state.

 Table 6a. Switch Routing Control Pin Setting for the MAX9134

PORT	S5	S4	S3	S2	S1	S0	CONNECTION	DESCRIPTION	
				Х	х	0	DOUT0 connected to DIN0		
						Open	DOUT0 connected to DIN1	Both DOUT0 and DOUT1 outputs are on	
	0	х	x			1	DOUT0 connected to DIN2		
	0	X	~		0		DOUT1 connected to DIN0		
					Open	Х	DOUT1 connected to DIN1		
					1		DOUT1 connected to DIN2		
DOUT0,						0	DOUT0 connected to DIN0		
DOUT1		Х	Х	Х	0	Open	DOUT0 connected to DIN1	DOUT1 is not connected, DOUT0 is on	
	1					1	DOUT0 connected to DIN2	DOUTO IS OIT	
	1	Х		х		0	DOUT1 connected to DIN0		
			Х		Open	Open	DOUT1 connected to DIN1	DOUT0 is not connected, DOUT1 is on	
						1	DOUT1 connected to DIN2	DOUTTISON	
	1	Х	х	х	1	х	DOUT0 and DOUT1 in high impedance	Both DOUT0 and DOUT1 are not connected	
	Х	0	х	0		x	DOUT2 connected to DIN0	Both DOUT2 and DOUT3	
				Open			DOUT2 connected to DIN1		
				1	N.		DOUT2 connected to DIN2		
			0		x		DOUT3 connected to DIN0	outputs are on	
			Open	Х			DOUT3 connected to DIN1		
			1				DOUT3 connected to DIN2		
DOUT2,				0			DOUT2 connected to DIN0		
DOUT3		1	0	Open	Х	Х	DOUT2 connected to DIN1	DOUT3 is not connected, DOUT2 is on	
	~			1			DOUT2 connected to DIN2	D001213011	
	Х		1 Open	0			DOUT3 connected to DIN0		
				Open	Х	Х	DOUT3 connected to DIN1	DOUT2 is not connected, DOUT3 is on	
				1			DOUT3 connected to DIN2		
	Х	1	1	х	х	х	DOUT2 and DOUT3 in high impedance	Both DOUT2 and DOUT3 are not connected	

X = Don't care.

Interface Selection Using S[5:0] (MAX9134/MAX9135)

S[5:0] determine which interface controls the MAX9134/MAX9135. Leave S[5:0] unconnected or set to a midlevel state to enable the LIN interface. Other settings to S[5:0] set the switch routing according to Tables 6a (MAX9134) and 6b (MAX9135). The I²C interface is active when the MAX9132/MAX9134/MAX9135 are not in LIN interface mode. Writing to an I²C register overrides the S[5:0] settings.

Interface Selection Using FS (MAX9132 Only)

The FS input selects the interface for the MAX9132. Set FS low for LIN interface control and FS high for I^2C interface. The MAX9132 powers up with all LVDS outputs unconnected for either mode.

Interfacing the MAX9132/MAX9134/MAX9135 to the LIN Bus

The MAX9132/MAX9134/MAX9135 interface to the LIN bus through the MAX13020 LIN transceivers. This device translates the +12V to +42V LIN bus signal down

14

MAX9132/MAX9134/MAX9135

PORT	S5	S4	S3	S2	S1	S0	CONNECTION	DESCRIPTION							
	0			x	×	0	DOUT0 connected to DIN0								
	0	Х	Х			Open	DOUT0 connected to DIN1	S5 and S0 determine							
DOUTO	0					1	DOUT0 connected to DIN2								
	1	х	x x		х	0	DOUT0 connected to DIN3								
	1	^	^	Х	^	Open	DOUT0 in high impedance								
	х	0			0	Х	DOUT1 connected to DIN0	S4 and S1 determine DOUT1 connection							
		0	Х	X Open	Open		DOUT1 connected to DIN1								
DOUT1		0			1		DOUT1 connected to DIN2								
		1	Х	х	0		DOUT1 connected to DIN3								
		1	^	^	Open		DOUT1 in high impedance								
										0	0			DOUT2 connected to DIN0	
DOUT2			0	Open			DOUT2 connected to DIN1								
	Х	Х	Х	0	1	Х	Х	DOUT2 connected to DIN2	S3 and S2 determine DOUT2 connection						
			1	0			DOUT2 connected to DIN3								
			1	Open			DOUT2 in high impedance								

Table 6b. Switch Routing Control Pin Setting for the MAX9135

X = Don't care.

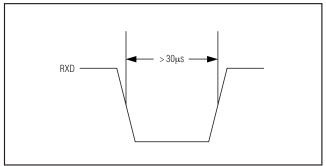
to the +3.3V logic level. Figure 5 shows the circuit that interfaces the crossbar switches to the LIN bus.

Waking Up the LIN Bus Driver

At power-up, the MAX9132/MAX9134/MAX9135 leave NSLP low, keeping the LIN bus driver in sleep mode. When the LIN driver receives a wake-up signal (Figure 6) from the LIN bus, the driver pulls RXD low. When the MAX9132/MAX9134/MAX9135 detect a falling edge on RXD, the device pulls NSLP high waking up the LIN driver. The MAX9132/MAX9134/MAX9135 then enable the TXD pin.

Putting the LIN Bus Driver into Sleep Mode

There are two conditions under which the MAX9132/ MAX9134/MAX9135 put the LIN driver to sleep: line activity timeout and receiving a sleep command. The first condition arises if there is inactivity on the LIN bus





M/IXI/N

Multiple MAX9132/MAX9134/MAX9135 for Port Expansion

The MAX9132/MAX9134/MAX9135 high-impedance outputs allow the attachment of several parts in parallel. Figure 7 shows example connection schemes to realize larger crossbar connections.

LVDS Output Preemphasis

The MAX9132/MAX9134/MAX9135 feature a preemphasis mode where extra current is added to the output and causes the amplitude to increase by 50% at the transition point. Preemphasis helps to get a faster transition, better eye diagram, and improved signal integrity (see the *Typical Operating Characteristics*). During data transition, the switch injects additional current for a short period, typically 400ps. Leave PD open or apply a midlevel voltage (VDD/2) to enable preemphasis on all LVDS outputs. Set PD high to set preemphasis through the I²C or LIN interfaces. Preemphasis in this mode is initially not on.

Power-Down

Set PD low to enable power-down mode. The registers retain their values and the device resumes operation from the same mode upon power-up.



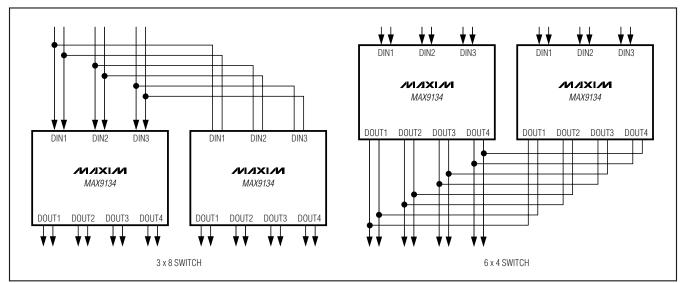


Figure 7. Topologies for Port Expansion

Input/Output Termination

Terminate LVDS inputs/outputs through 100Ω differential termination, or use an equivalent Thevenin termination. Terminate both inputs/outputs and use identical terminations on each for the lowest output-to-output skew.

Power-Supply Bypassing

Adequate power-supply bypassing is necessary to maximize the performance and noise immunity. Bypass each supply to their respective grounds with high-frequency surface-mount 0.01μ F ceramic capacitors as close as possible to the device. Use multiple bypass vias for connection to minimize inductance.

Board Layout

Separate the I²C/LIN signals and LVDS signals to prevent crosstalk. When possible, use a four-layer PCB with separate layers for power, ground, LVDS, and digital signals. Layout PCB traces for 100Ω differential characteristic impedance. The trace dimensions depend on the type of trace used (microstrip or stripline).

Route the PCB traces for an LVDS channel (there are two conductors per LVDS channel) in parallel to maintain the differential characteristic impedance. Place the 100 Ω (typ) termination resistor at both ends of the LVDS driver and receiver. Avoid vias. If vias must be used, use only one pair per LVDS channel and place the via for each line at the same point along the length of the PCB traces. This way, any reflections occur at the same time. Do not make vias into test points for

automated test equipment. Make the PCB traces that make up a differential pair the same length to avoid skew within the differential pair.

Cables and Connectors

Interconnect for LVDS typically has a differential impedance of 100 Ω . Use cables and connectors that have matched differential impedance to minimize impedance discontinuities. Twisted-pair and shielded twisted-pair cables offer superior signal quality compared to ribbon cable and tend to generate less EMI due to magnetic-field-canceling effects. Balanced cables pick up noise as common mode that is rejected by the LVDS receiver. Add a 0.1µF capacitor in series with each output for AC-coupling.

Choosing Pullup Resistors

I²C requires pullup resistors to provide a logic-high level to data and clock lines. There are tradeoffs between power dissipation and speed, and a compromise must be made in choosing pullup resistor values. Every device connected to the bus introduces some capacitance even when the device is not in operation. I²C specifies 300ns rise times to go from low to high (30% to 70%) for fast mode, which is defined for a data rate up to 400kbps (see the *I*²*C Interface* section for details). To meet the rise time requirement, choose the pullup resistors so that the rise time tR = 0.85RPULLUP x C_{BUS} < 300ns. If the transition time becomes too slow, the setup and hold times may not be met and waveforms are not recognized.

Exposed Pad

The TQFP and TSSOP packages used for the MAX9132/MAX9134/MAX9135 have exposed pads on the bottom. The exposed pad is internally connected to ground. Connect the exposed pad to ground using a landing pad large enough to accommodate the entire exposed pad. Add vias from the exposed pad's land area to a copper polygon on the other side of the PCB to provide lower thermal impedance from the device to the ambient air.

ESD Protection

The MAX9132/MAX9134/MAX9135 ESD tolerance is rated for IEC 61000-4-2, Human Body Model, and ISO 10605 standards. IEC 61000-4-2 and ISO 10605 specify ESD tolerance for electronic systems. The IEC 61000-4-2 discharge components are Cs = 150pF and RD = 330Ω (Figure 8). For IEC 61000-4-2, the LVDS outputs are rated for ±10kV Contact Discharge and ±15kV Air-Gap Discharge. The Human Body Model

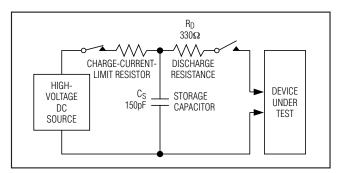


Figure 8. IEC 61000-4-2 Contact Discharge ESD Test Circuit

discharge components are Cs = 100pF and R_D = 1.5k Ω (Figure 9). For the Human Body Model, all pins are rated for ±2kV Contact Discharge. The ISO 10605 discharge components are Cs = 330pF and R_D = 2k Ω (Figure 10). For ISO 10605, the LVDS outputs are rated for ±10kV Contact and ±25kV Air-Gap Discharge.

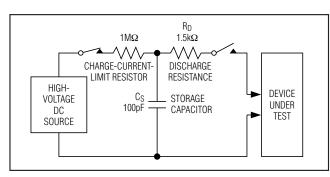


Figure 9. Human Body ESD Test Circuit

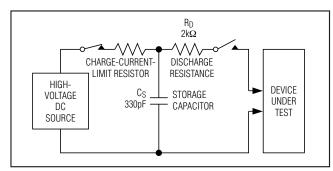
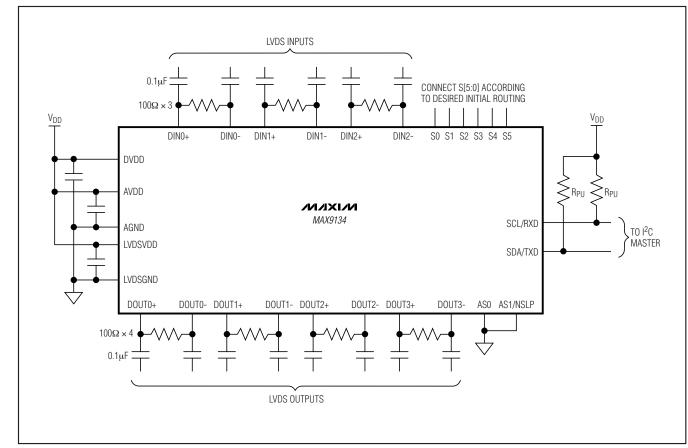
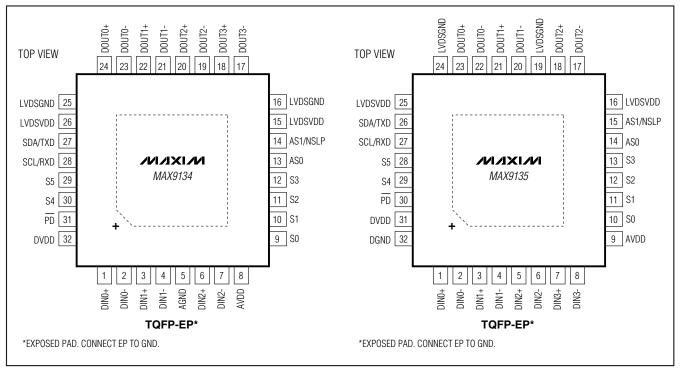


Figure 10. ISO 10605 Contact Discharge ESD Test Circuit

Typical Application Circuit



Pin Configurations (continued)



Chip Information

PROCESS: CMOS

Package Information

For the latest package outline information and land patterns (footprints), go to <u>www.maxim-ic.com/packages</u>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
20 TSSOP-EP	U20E+1	<u>21-0108</u>	<u>90-0114</u>
32 TQFP-EP	H32E+6	<u>21-0079</u>	<u>90-0326</u>



Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	7/08	Initial release	_
1	2/11	Updated <i>Pin Control by S</i> [5:0] (MAX9134/MAX9135) and <i>Interface Selection Using FS</i> (MAX9132 Only) sections	13, 14
2	4/11	Added automotive part (MAX9132) to Ordering Information	1

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

Maxim Integrated Products, 120 San Gabriel Drive, Sunnyvale, CA 94086 408-737-7600

© 2011 Maxim Integrated Products

Maxim is a registered trademark of Maxim Integrated Products, Inc.

_ 20

Downloaded from: http://www.datasheetcatalog.com/